



## Product Change Notice

Micron PCN: 30443

Date: 4/27/2011

<b>Type of Change:</b>	End of Life	
<b>Title of Change:</b>	M62B 34nm SLC NAND Flash Technology Change	
<b>Description of Change:</b>	Micron's SLC NAND Flash devices described below are moving from 34nm to 25nm process technology. The 25nm process technology features a monolithic 32Gb device (M73A) that will be stacked to achieve densities up to 256Gb in a single package.	
<b>Reason for Change:</b>	Optimization of Manufacturing Efficiency	
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**Product Affected:** 16Gb monolithic device (M62B), 32Gb DDP packaged device (M62B), 64Gb QDP packaged device (M62B), 128Gb 8DP packaged device (M62B)

Affected Micron Part Numbers	Replacement Part Numbers
<b>Wafer</b>	
MT29F16G08ABABAM62B3WC1	MT29F16G08ABACAM72A3WC1
MT29F16G08ABCBBM62B3WC1	MT29F16G08ABACAM72A3WC1
MT29F16G08ABEBBM62B3WC1	MT29F16G08ABACAM72A3WC1
<b>Component</b>	
MT29F128G08AUABAC5-IT:B	MT29F128G08AMAAAC5-IT:A
MT29F128G08AUABAC5:B	MT29F128G08AMAAAC5:A
MT29F128G08AUCBBH3-12:B	MT29F128G08AMCABH2-10:A
MT29F128G08AUCBBH3-12IT:B	MT29F128G08AMCABH2-10IT:A
MT29F16G08ABABAWC:B	MT29F16G08ABACAWP:C
MT29F16G08ABABAWP-IT:B	MT29F16G08ABACAWP-IT:C
MT29F16G08ABABAWP:B	MT29F16G08ABACAWP:C
MT29F16G08ABCBBH1-12:B	MT29F16G08ABCCBH1-12:C
MT29F16G08ABCBBH1-12IT:B	MT29F16G08ABCCBH1-12IT:C
MT29F32G08ADCBBH1-12:B	MT29F32G08ABCABH1-10:A
MT29F32G08AECBBH1-12:B	MT29F32G08ABCABH1-10:A
MT29F32G08AECBBH1-12IT:B	MT29F32G08ABCABH1-10IT:A
MT29F32G08AFABAWP-IT:B	MT29F32G08ABAAAWP-IT:A
MT29F32G08AFABAWP:B	MT29F32G08ABAAAWP-IT:A
MT29F64G08AJABAWP-IT:B	MT29F64G08AFAAAWP-IT:A
MT29F64G08AJABAWP:B	MT29F64G08AFAAAWP:A
MT29F64G08AKABAC5-IT:B	MT29F64G08AEAAAC5-IT:A
MT29F64G08AKABAC5:B	MT29F64G08AEAAAC5:A
MT29F64G08AKCBBH2-12:B	MT29F64G08AECABH1-10:A
MT29F64G08AKCBBH2-12IT:B	MT29F64G08AECABH1-10IT:A
MT29F64G08AKCBBH3-12:B	MT29F64G08AECABH1-10:A

Note: Per JEDEC Standard JESD46-C Section 3.2.3; lack of acknowledgment of this PCN within 30 days constitutes acceptance of change



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MT29F64G08AKCBBH3-12IT:B	MT29F64G08AECABH1-10IT:A
MT29F64G08AMABAC5-IT:B	MT29F64G08AEAAAC5-IT:A
MT29F64G08AMABAC5:B	MT29F64G08AEAAAC5:A
MT29F64G08AMCBBH2-12:B	MT29F64G08AECABH1-10:A
MT29F64G08AMCBBH2-12IT:B	MT29F64G08AECABH1-10IT:A

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**Method of Identification:** Marketing part number. Please refer to the table above for differences between the part numbers affected by this technology change and recommended replacement marketing part numbers.

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**Micron Sites Affected:** All Sites

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**25nm Product (M73A)**

*Product Ship Date:* Now  
*Samples Available:* Now  
*Qual Data Available:* Now

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**34nm Product (M62B)**

*Last Time Buy:* 26-Oct-2011  
*Last Time Ship:* 26-Apr-2012

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**Qualification Plan:**

The 25nm process technology and stacked package was qualified according to Micron's qualification procedure and best practices. The qualification plan is be available upon request.

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